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Insulation Resistance: 1,000M $\Omega$  min. at 100V DC Dielectric Withstanding Voltage: 100V AC for 1 minute

Polyetherssulphone (PES), glass-filled

Contact Resistance:  $100m\Omega$  max. at 10mA/20mV max.

Operating Temperature Range: -40°C to +150°C Contact Force: 10gf per pin approx.

Operating Force:  $2.2kq \pm 0.5$ 

Housing: Polyetherimide (PEI), glass-filled



#### **Features**

- Open top socket for BGA
- Through hole 0.5mm pitch
- 2-point Tweezer Contacts

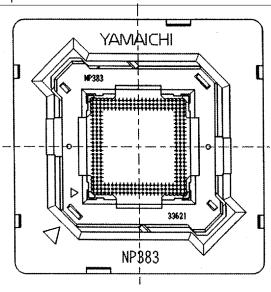


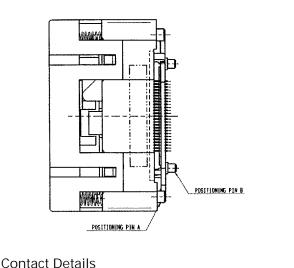
#### **Example Socket Dimensions**

Plating: Gold over Nickel

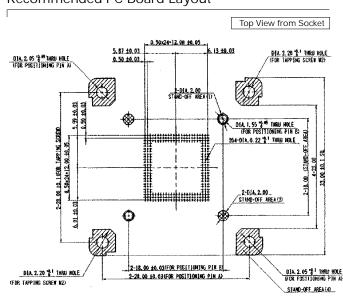
Contacts: Beryllium Copper (BeCu)

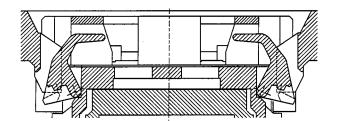
Materials and Finish



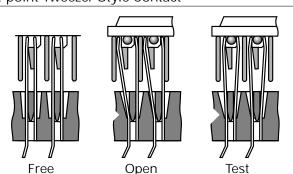


## Recommended PC Board Layout





### 2-point Tweezer Style Contact



Part Number	Grid Size	Body size	Socket Dimensions	Centre Grid size
NP383-18010-*	10x18	11.0x12.5	19.5x26.0	no grid centre
NP383-28804-*	18x18	10.0x10.0	36.0x36.0	6x6
NP383-84107-*	29x29	15.0x15.0	33.0x33	7x7